1. (currently amended): A method for fabricating a slider comprising the steps of:

fabricating a plurality of transducers on a wafer ~~including an overcoat layer~~;

~~etching a trench in the overcoat layer; and~~

slicing the wafer into slider bars having a plurality of sliders formed therealong and fabricating air bearing surfaces for the plurality of sliders along the slider bar ~~having a trailing edge defined by a recessed surface of the etched trench~~; and

etching a trench prior to slicing the wafer to form a trailing edge of the air bearing surfaces of the plurality of sliders.

2. (currently amended): The method of claim 1 ~~wherein~~and further comprising the step of

depositing an ~~the~~ overcoat layer prior to slicing the wafer ~~is an Alumina overcoat layer~~ and forming the trench ~~is formed~~ in the ~~Alumina~~ overcoat layer.

3. (original): The method of claim 1 wherein the air bearing surfaces of the plurality of sliders along the slider bar are formed using a photoalignment masking process.

4. (currently amended): The method of claim 1 wherein ~~the~~ a recessed surface of the trench forms ~~a~~ the trailing edge for ~~a~~ the raised bearing surfaces of the sliders.

5. (original): The method of claim 1 and further comprising the step of:

planarizing the slider or wafer prior to etching the trench.

6. (original): A method for fabricating a slider comprising the step of:

fabricating a trench having a recessed trench surface spaced from a trailing end surface of the slider to form a trailing edge of a raised bearing surface of the slider defined by an etched depth of the trench of the slider.

7. (original): The method of claim 6 wherein the trench is fabricated at a wafer level prior to slicing the wafer into slider bars to form a plurality of sliders therealong.

8. (original): The method of claim 7 and further comprising the step of:

forming air bearing surfaces on the slider bar after slicing the slider bar from the wafer.

9. (original): A head comprising:

a slider having a transducer portion fabricated proximate a trailing end of the slider; and

a trench in an overcoat layer of the transducer portion forming a trailing edge of the slider and the trailing edge having a recessed dimension relative to a trailing end surface of the slider defined by an etched depth of the trench of the slider.

10. (cancelled)

11. (original): The head of claim 9 wherein the transducer portion includes inductive and/or magnetoresistive transducer elements.

12. (original): The head of claim 9 wherein the trench forms a trailing edge of a raised bearing surface of the slider.

13. (new): The method of claim 6 wherein the trench is fabricated in one process step and comprising the step of:

fabricating a raised bearing surface and a recessed bearing surface on a disc facing surface of the slider in another process step and the raised bearing surface in the other process step having a trailing edge defined by the trench fabricated in the one process step.

14. (new): The method of claim 13 and further comprising the step of:

planarizing or lapping the disc facing surface of the slider in addition to the one process step and the other process step.

15. (new): The method of claim 14 and further comprising the step of planarizing or lapping the disc facing surface of the slider prior to the other process step and after the one process step.

16. (new): The method of claim 13 wherein the raised bearing surface and the recessed bearing surface are formed using a photoalignment masking process in the other process step.

17. (new): The method of claim 13 wherein the trench is etched in the one process step prior to forming the raised bearing surface and the recessed bearing surface in the other process step.

18. (new): The method of claim 13 wherein the raised bearing surface and the recessed bearing surface and the trailing edge of

the raised bearing surface are etched relative to different orthogonal surfaces of the slider in the one and the other process steps.

19. (new): The method of claim 13 and further comprising:
etching the trench relative to a first orientation in the one process step; and
etching the recessed bearing surface relative to a second orientation in the other process step.

20. (new): A slider formed from the method of claim 6.

21. (new): A slider formed from the method of claim 1.